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High Stability - High Temperature (230 °C) Thin Film Wraparound Chip Resistors, Sulfur Resistant



DESIGN SUPPORT TOOLS

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INTRODUCTION

For applications such as down hole applications, the need for parts able to withstand very severe conditions (temperature as high as 215 °C powered or up to 230 °C un-powered) has leaded Vishay Sfernice to push out the limit of the thin film technology.

Designers might read the application note: Power Dissipation Considerations in High Precision Vishay Sfernice Thin Film Chip Resistors and Arrays (P, PRA etc...) (High Temperature Application) www.vishay.com/doc?53047 in conjunction with this datasheet to help them to properly design their PCBs and get the best performances of the PHT.

Vishay Sfernice R&D engineers will be willing to support any customer design considerations.

FEATURES

- Operating temperature range: -55 °C; +215 °C
- Storage temperature: -55 °C; +230 °C
- Gold terminations (< 1 µm thick)
- 5 sizes available (0402, 0603, 0805, 1206, 2010); other sizes upon request
- Temperature coefficient down to 15 ppm (-55 °C; +215 °C)
- Tolerance down to 0.05 %
- Load life stability: 0.35 % max. after 2000 h at 220 °C (ambient) at Pn
- Shelf life stability: 0.7 % typ. (1 % max.) after 15 000 h at 230 °C
- SMD wraparound
- TCR remains constant after long term storage at 230 °C (15 000 h)
- Sulfur resistant (per ASTM B809-95 humid vapor test)
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

STANDA	STANDARD ELECTRICAL SPECIFICATIONS							
MODEL	SIZE	RESISTANCE RANGE Ω	RATED POWER (1)(2) <i>P</i> _{215 °C} W	LIMITING ELEMENT VOLTAGE V	TOLERANCE (2) ± %	TEMPERATURE COEFFICIENT (3) ± ppm/°C		
PHT0402	0402	10 to 130K	0.0189	50	0.05, 0.1, 0.5, 1	10, 15, 25, 30, 50, 55		
PHT0603	0603	10 to 320K	0.0375	75	0.05, 0.1, 0.5, 1	10, 15, 25, 30, 50, 55		
PHT0805	0805	10 to 720K	0.06	150	0.05, 0.1, 0.5, 1	10, 15, 25, 30, 50, 55		
PHT1206	1206	10 to 2.7M	0.1	200	0.05, 0.1, 0.5, 1	10, 15, 25, 30, 50, 55		
PHT2010	2010	10 to 7.5M	0.2 (4)	300	0.05, 0.1, 0.5, 1	10, 15, 25, 30, 50, 55		

Notes

- (1) For power handling improvement, please refer to application note 53047: "Power Dissipation Considerations in High Precision Vishay Sfernice Thin Film Chip Resistors and Arrays (High Temperature Applications)" www.vishay.com/doc?53047 and consult Vishay Sfernice
- (2) See Table 2 on next page
- (3) See Table 1 on next page

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(4) It is possible to dissipate up to 0.3 W, but there will be an additional drift of 0.1 % after load life

CLIMATIC SPECIFICA	TIONS
Operating temperature range	-55 °C; +215 °C
Storage temperature range	-55 °C; +230 °C

PERFORMANCE VS. HUMID SULFUR VAPOR					
Test conditions	50 °C \pm 2 °C, 85 % \pm 4 % RH, exposure time 500 h				
Test results	Resistance drift < (0.05 % R + 0.05 Ω), no corrosion products observed				

MECHANICAL SPECIFICATIONS				
Substrate	Alumina			
Resistive Element	Nichrome (NiCr)			
Passivation	Silicon nitride (Si ₃ N ₄)			
Protection	Epoxy + silicone			
Terminations	Gold (< 1 µm) over nickel barrier			

Note

For other terminations, please consult

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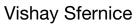
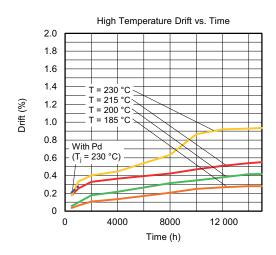




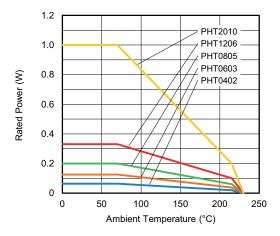
TABLE 1 - TEMPERATURE COEFFICIENT					
V	10 ppm/°C	-55 °C; +155 °C			
'	15 ppm/°C	-55 °C; +215 °C			
F	25 ppm/°C	-55 °C; +155 °C			
	30 ppm/°C	-55 °C; +215 °C			
Н	50 ppm/°C	-55 °C; +155 °C			
	55 ppm/°C	-55 °C; +215 °C			

TABLE 2 - BEST TOLERANCE AND TCR VS. OHMIC VALUE					
SERIES	RANGE (Ω)	TOL. (± %)	TCR CODE		
	10 to 50	0.1; 0.5; 1	Y; E; H		
0402	> 50 to 90K	0.05; 0.1; 0.5; 1	Y; E; H		
	> 90K to 130K	0.05; 0.1; 0.5; 1	E; H		
	10 to 50	0.1; 0.5; 1	Y; E; H		
0603	> 50 to 210K	0.05; 0.1; 0.5; 1	Y; E; H		
	> 210K to 320K	0.05; 0.1; 0.5; 1	E; H		
	10 to 50	0.1; 0.5; 1	Y; E; H		
0805	> 50 to 480K	0.05; 0.1; 0.5; 1	Y; E; H		
	> 480K to 720K	0.05; 0.1; 0.5; 1	E; H		
	10 to 50	0.1; 0.5; 1	Y; E; H		
1206	> 50 to < 1.8M	0.05; 0.1; 0.5; 1	Y; E; H		
	> 1.8M to 2.7M	0.05; 0.1; 0.5; 1	E; H		
	10 to 50	0.1; 0.5; 1	Y; E; H		
2010	> 50 to 5M	0.05; 0.1; 0.5; 1	Y; E; H		
	> 5M to 7.5M	0.05; 0.1; 0.5; 1	E; H		

PHT STABILITY CURVE



POWER DERATING CURVE

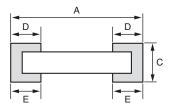


Note

 Stability will be dependent on resistivity of resistor. Above curves are worst case.



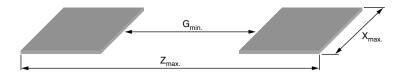
DIMENSIONS in millimeters (inches)





	Α	В		D/E	
CASE SIZE	MAX. TOL. +0.152 (+0.006) MIN. TOL. -0.152 (-0.006)	MAX. TOL. +0.127 (+0.005) MIN. TOL. -0.127 (-0.005)	С		
	NOMINAL	NOMINAL		NOMINAL	TOLERANCE
0402	1.00 (0.039)	0.60 (0.024)	Termination N:	0.25 (0.010)	0.1 (0.004)
0603	1.52 (0.060)	0.85 (0.033)	0.5 (0.02) ± 0.127 (0.005)	0.38 (0.015)	
0805	1.91 (0.075)	1.27 (0.050)	, ,	0.38 (0.013)	0.13 (0.005)
1206	3.06 (0.120)	1.60 (0.063)	Termination G: 0.4 (0.016)	0.40 (0.016)	0.13 (0.005)
2010	5.08 (0.200)	2.54 (0.100)	± 0.051 (0.002)	0.48 (0.019)	

SUGGESTED LAND PATTERN (TO IPC-7351A)



CHIP SIZE	DIMENSIONS (in millimeter)				
CHIP SIZE	Z _{max.}	G _{min.}	X _{max.}		
0402	1.55	0.15	0.73		
0603	2.37	0.35	0.98		
0805	2.76	0.74	1.40		
1206	3.91	1.85	1.73		
2010	5.93	3.71	2.67		

Caution:

Performances obtained with following mounting conditions:

PCB: polyimide

Solder paste: PbSnAg (93.5/5/1.5)



POPULAR OPTIONS

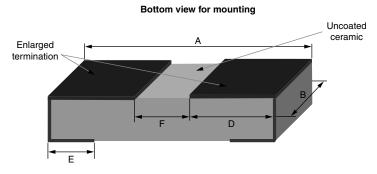
It is recommended to consult Vishay Sfernice for availability first.

Option: Enlarged terminations:

For stringent and special power dissipation requirements, the thermal resistance between the resistive layer and the solder joint can be reduced using enlarged terminations chip resistors which are soldered on large and thick copper pads acting as heatsink (see application note: 53048 "Power Dissipation in High Precision Vishay Sfernice Chip Resistors and Arrays (P Thin Film, PRA Arrays, CHP Thick Film)" www.vishay.com/doc?53048.

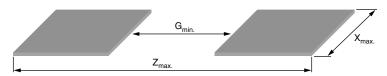
Option to order: 0063 (applies to size 1206 / 2010).

DIMENSIONS (Option 0063) in millimeters



	Α	В	E	D			
CASE SIZE	MAX. TOL. +0.152 MIN. TOL. -0.152	MAX. TOL. +0.127 MIN. TOL. -0.127	MAX. TOL. +0.13 MIN. TOL. -0.13	MAX. TOL. +0.13 MIN. TOL. -0.13		F	
	NOMINAL	NOMINAL	NOMINAL	NOMINAL	NOMINAL	MIN.	MAX.
1206	3.06	1.60	0.40	1.215	0.63	0.50	0.76
2010	5.08	2.54	0.48	2.25	0.03		0.76

SUGGESTED LAND PATTERN (Option 0063)



CHIP SIZE	DIMENSIONS (in millimeter)				
CHIP SIZE	Z _{max.}	G _{min.}	X _{max.}		
1206	3.91	0.50	1.73		
2010	5.93	0.30	2.67		



PACKAGING

ESD packaging available: waffle-pack and plastic tape and reel (low conductivity). Paper tape available upon request (for sizes 0402, 0603, 0805 and 1206).

		NUMBER OF PIE			
SIZE	MOQ	WAFFLE PACK	TAPE A	TAPE WIDTH	
		2" × 2"	MIN.	MAX.	
0402				5000	
0603		100		3000	0
0805	100		100	4000	8 mm
1206		140		4000	
2010		60		1000	8 mm ⁽¹⁾

Note

(1) 12 mm on request

PACKAGING RULES

Waffle Pack

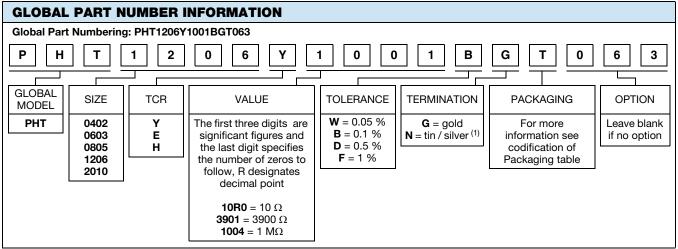
Can be filled up to maximum quantity indicated in the table here above, taking into account the minimum order quantity. When quantity ordered exceeds maximum quantity of a single waffle pack, the waffle packs are stacked up on the top of each other and closed by one single cover.

To get "not stacked up" waffle pack in case of ordered quantity > maximum number of pieces per package: Please consult Vishay Sfernice for specific ordering code.

Tape and Reel

Can be filled up to maximum quantity indicated in the table here above, taking into account the minimum order quantity. When quantity ordered is between the MOQ and the maximum reel capacity, only one reel is provided.

When several reels are needed for ordered quantity within MOQ and maximum reel capacity: please consult Vishay Sfernice for specific ordering code.



Note

(1) For usage at temperatures up to 200 °C maximum N (tin/silver termination are available upon request)

CODIFICATION OF PACKAGING					
CODE 18	PACKAGING				
WAFFLE PACK					
W	100 min., 1 mult				
WA	100 min., 100 mult (available only on size 1206)				
PLASTIC TAPE (in standard for al	ll sizes)				
Т	100 min., 1 mult				
TA	100 min., 100 mult				
TB	250 min., 250 mult				
TC	500 min., 500 mult				
TD	1000 min., 1000 mult				
TE	2500min., 2500 mult				
TF	Full tape (quantity depending on size of chips)				
PAPER TAPE (Available for 0402,	0603, 0805 and 1206. Please consult Vishay Sfernice for 2010 size.)				
PT	100 min., 1 mult				
PA	100 min., 100 mult				
PB	250 min., 250 mult				
PC	500 min., 500 mult				
PD (not available for size 0402)	1000 min., 1000 mult				
PE (not available for size 0402)	2500min., 2500 mult				
PF (not available for size 0402)	Full tape (quantity depending on size of chips)				

Revision: 03-Jan-2019 5 Document Number: 53050 For technical questions, contact: <u>sferthinfilm@vishay.com</u>



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PHT0603Y2212BG	PHT0603Y1000BG	PHT0805Y1003BGT	PHT1206Y1001BGT	PHT1206Y1004BGT
PHT0805Y1001BGT	PHT1206Y1000BGT	PHT2010Y1003BGT	PHT0805Y1002BGT	PHT1206Y1003BGT
PHT2010Y1000BGT	PHT2010Y1001BGT	PHT1206Y1002BGT	PHT0805Y1000BGT	PHT0603Y1001BGT
PHT0603Y1003BGT	PHT0603Y1002BGT	PHT0603E10R0DGT	PHT0805E10R0DGT	PHT1206E10R0DGT
PHT0603Y4992BGT	PHT1206Y1001BNT	PHT0402E1001BGPT	PHT0402E2002BGF	PT